



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: A1902-03		DATE: 12-Mar-2019	MEANS OF DISTINGUISHING CHANGED DEVICES:
Product Affected: 4RCD0124KC0ATG(8) 4RCD0124KC0ATGI(8) 4RCD0124KC0ATG8/B 4RCD0124KC0ATG8/M			☐ Product Mark ☒ Back Mark ☐ Date Code ☐ Other
Date Effective: 12-Jun-2019			Lot # will have: "RC" prefix for ASECL, Taiwan
Contact: IDT PCN DESK	Attachment: ☒ Yes ☐ No		
E-mail: pcndesk@idt.com	Samples: Please contact your local sales representative for sample request.		

DESCRIPTION AND PURPOSE OF CHANGE:

- | | |
|--|--|
| ☐ Die Technology | |
| ☐ Wafer Fabrication Process | This notification is to advise our customers that IDT is adding ASECL as an alternate assembly facility. |
| ☐ Assembly Process | |
| ☐ Equipment | |
| ☒ Material | There is no change to the moisture performance. |
| ☐ Testing | |
| ☒ Manufacturing Site | Attachment I details the qualification results. |
| ☐ Data Sheet | |
| ☐ Other | |

RELIABILITY/QUALIFICATION SUMMARY:

Refer to qualification data shown in Attachment I.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____	☐ <i>Approval for shipments prior to effective date.</i>
Name/Date: _____	E-Mail Address: _____
Title: _____	Phone# /Fax# : _____

CUSTOMER COMMENTS:

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____



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ATTACHMENT I - PCN # : A1902-03

PCN Type: Manufacturing Site - Alternate Assembly Location

Data Sheet Change: None

No change in moisture sensitivity level (MSL)

Detail Of Change:

This notification is to advise our customers that IDT is adding ASECL as an alternate assembly facility.

The material set details of the current and alternate assembly location is as shown in Table 1.

There is no change to the moisture performance.

Table 1: Assembly Material Sets for The Existing and Alternate Assembly Location

	Existing Assembly (Amkor, Philippines)	Existing Assembly (ASEK, Taiwan)	Alternate Assembly (ASECL, Taiwan)
Die Bump	Sn1.8Ag	Sn1.8Ag	Sn1.8Ag
Mold Compound	GE100-RFC32	KE-G1250FC-20B	KE-G1250FC-20B
Substrate	UMTC E700/AUS703	UMTC E700/AUS703 Kinsus E700/AUS703	UMTC E700/AUS703 Kinsus E700/AUS703
Solder Balls	Sn96.5/Ag3.0/Cu0.5	Sn96.5/Ag3.0/Cu0.5	Sn96.5/Ag3.0/Cu0.5



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ATTACHMENT I - PCN # : A1902-03

Qualification Information and Qualification Data:

Affected Packages: FCCSP-253

Assembly Material: Shown on page 2 of this attachment.

Qual Plan & Results: Tests are in accordance with JEDEC47 recommended tests.

Qualification Vehicle: FCCSP-253

Test Description	Test Method	Test Results (Rej / SS)		
		Lot 1	Lot 2	Lot 3
* Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0/25	0/25	0/25
* HAST - biased (130 °C/85% RH, 96 Hrs)	JESD22-A110	0/25	0/25	0/25
High Temperature Storage Bake (150°C, 1000 Hrs)	JESD22-A103	0/25	0/25	0/25
Solder Ball Shear Test	JESD22-B117	0/5	0/5	0/5
Moisture Sensitivity Level, MSL	J-STD-20 / MSL 3, 260 °C	0/25	0/25	-

* Tests were subjected to Preconditioning per JESD22-A113 prior to stress test